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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. Nakamura, et al.
Application No.: TBD
Filed: June 25, 2004
For: CONNECTION BOARD, AND MULTI-LAYER WIRING BOARD,
SUBSTRATE FOR SEMICONDUCTOR PACKAGE AND
SEMICONDUCTOR PACKAGE USING CONNECTION
BOARD, AND MANUFACTURING METHOD THEREOF
Group: Unassigned
Examiner: Unassigned

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR § 1.97 AND § 1.98

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 25, 2004

Sir:

Pursuant to Applicants' duty of disclosure, enclosed please find an International Search Report, and copies of documents cited therein, in connection with International (PCT) Application No. PCT/JP02/13434, filed December 24, 2002. Please note that the above-identified application is a National Stage application, filed under 35 USC §371, of No. PCT/JP02/13434. Also enclosed are copies of two publications discussed under the "BACKGROUND OF THE INVENTION" of the above-identified application, in the paragraph bridging pages 2 and 3 thereof. Also enclosed is Taiwanese Patent Document No. 444529, cited in an Official Action in connection with a counterpart patent application in Taiwan, as well as an English-language Abstract of Japanese Patent Document No. 2000-100987 which is a

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DT04 Rec'd PCT/PTO 25 JUN 2004

counterpart to the Taiwanese patent document.

Further enclosed herewith is a Form, substantially equivalent to Form PTO-1449, listing all of the enclosed documents.

This Information Disclosure Statement is being submitted concurrently with the filing of the above-identified application. Clearly, requirements of 37 CFR § 1.97(b) are satisfied.

To the extent that the enclosed documents are not in English, it is respectfully submitted that, with respect to the documents cited in the enclosed International Search Report, requirements of 37 CFR § 1.98(a)(3) are satisfied by the English-language version of the International Search Report citing, where appropriate, relevant passages of the documents, and/or by English-language Abstracts of the non-English language documents. In connection with the presently submitted two publications, requirements of 37 CFR § 1.98(a)(3) are satisfied by discussion of these documents in the specification of the above-identified application, e.g., in the paragraph bridging pages 2 and 3 thereof. With respect to the presently submitted Taiwanese patent document, requirements of 37 CFR § 1.98(a)(3) are satisfied by the English-language Abstract of Japanese Patent Document No. 2000-100987, a publication of an application corresponding to that of the Taiwanese patent document.

In view of all of the foregoing, it is respectfully submitted that all applicable requirements of 37 CFR § 1.97 and § 1.98 have been satisfied, in connection with all documents listed on the enclosed Form. Accordingly, consideration of the listed documents, upon examination of the above-identified application, is respectfully

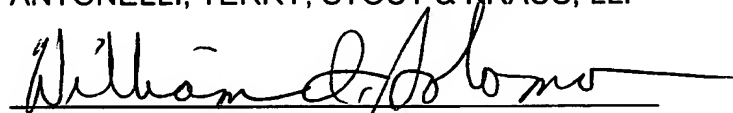
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DT04 Rec'd PCT/PTO 25 JUN 2004

requested.

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to the Deposit Account No. 01-2135 (Case No. 1204.43988X00), and please credit any excess fees to such Deposit Account.

Respectfully submitted,

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Substitute for form 1449A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Application Number	TBD
		Filing Date	June 25, 2004
		First Named Inventor	HIDEHIRO NAKAMURA
		Art Unit	TBD
		Examiner Name	TBD
Sheet 1 of 1	Attorney Docket Number	1204.43988X00	

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		US-			
		US-			
		US-			

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document Country Code ³ -Number ⁴ - Kind Code ⁵ (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	Abstract/ Translation
		JP- 2001-326458	11/22/2001	Matsushita Electric Ind. Co		X
		JP-11-251703	9/17/1999	Matsushita Electric Ind. Co		X
		JP-2001-326459	11/22/2001	North:KK		X
		JP-2001-015920	1/19/2001	Toshiba Corp.		X
		JP-06-350258	12/22/1994	Toshiba Corp.		X
		JP-2001-036250	2/9/2001	Mitsubishi Electric Corp.		X
		JP-2000-101248	4/7/2000	Ibiden Co., Ltd.		X
		JP-2000-286554	10/13/2000	Yamaichi Electronics Co., Ltd.		X
		TW-444529	9/17/1999	NEC Corp.		Abstract (equiv.)

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		International Search Report mailed 15 April 2003 for No. PCT/JP02/13434	
		Hiroshi Ohira, et al., "Suggestion of Printed Wiring Board by New Manufacturing Method", A Collection of Papers at the Ninth Lecture Meeting Regarding Circuit Mount, ISSN 0916-0043, 15A-10, pp. 55-56, (1995.3.14-16)	
		Takahiro Mori, et al. "Application and Miniaturization of Substrate Using Inter-Layer Connection Technique Using Bump", A Collection of Papers at the Tenth Lecture Meeting Regarding Circuit Mount ISSN 0916-0043, 15A-09, pp. 79-80, (1996.3.13-15)	
Examiner Signature		Date Considered	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

This collection of information is required by 37 CFR 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 120 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing the this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2